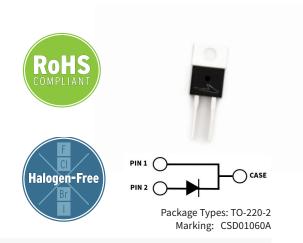


## 600 V, 1 A Silicon Carbide Schottky Diode

## Description

With the performance advantages of a Silicon Carbide (SiC) Schottky Barrier diode, power electronics systems can expect to meet higher efficiency standards than Si-based solutions, while also reaching higher frequencies and power densities. SiC diodes can be easily paralleled to meet various application demands, without concern of thermal runaway. In combination with the reduced cooling requirements and improved thermal performance of SiC products, SiC diodes are able to provide lower overall system costs in a variety of diverse applications.



#### **Features**

- $\hbox{ \bullet } \quad \hbox{Low Forward Voltage } (V_{F}) \ \hbox{Drop with Positive} \\ \hbox{Temperature Coefficient}$
- Zero Reverse Recovery Current / Forward Recovery Voltage
- Temperature-Independent Switching Behavior

## **Applications**

- Industrial Switched Mode Power Supplies
- Uninterruptible & AUX Power Supplies
- Boost for PFC & DC-DC Stages
- Solar Inverters

# **Maximum Ratings** ( $T_c = 25^{\circ}$ C Unless Otherwise Specified)

Parameter	Symbol	Value	Unit	Test Conditions	Notes
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	600			
DC Blocking Voltage	V <sub>DC</sub>	600	V		
		4		T <sub>J</sub> = 25 °C	
Continuous Forward Current	I <sub>F</sub>	2		T <sub>J</sub> = 135 °C	Fig. 3
		1		T <sub>J</sub> = 158 °C	
Repetitive Peak Forward Surge	.	7		T <sub>C</sub> = 25 °C, t <sub>p</sub> = 10 ms, Half Sine Wave	
Current	FRM	5.5	A	$T_{c} = 110 ^{\circ}\text{C}, t_{p} = 10 \text{ms},  \text{Half Sine Wave}$	
Non-Repetitive Forward Surge Current	I <sub>FSM</sub>	9		$T_c = 25 ^{\circ}\text{C}$ , $t_p = 1.5 \text{ms}$ , Half Sine Wave	Fig. 8
Non-Repetitive Peak Forward Surge Current	I <sub>F,Max</sub>	32		$T_{c} = 25 {}^{\circ}\text{C},  t_{p} = 10 \mu\text{s},  \text{Pulse}$	
D		21.4		T <sub>J</sub> = 25 °C	F: 4
Power Dissipation	P <sub>tot</sub>	7.1	W	T <sub>J</sub> = 125 °C	Fig. 4

## **Electrical Characteristics**

Parameter	Symbol	Тур.	Max.	Unit	Test Conditions	Notes
Forward Voltage		1.6	1.8	V	I <sub>F</sub> = 1 A, T <sub>j</sub> = 25 °C	Fig. 1
	V <sub>F</sub>	2.0	2.4		I <sub>F</sub> = 1 A, T <sub>j</sub> = 175 °C	
Reverse Current		20	100	μА	$V_R = 600 \text{ V}, T_j = 25 \text{ °C}$	Fig. 2
	I <sub>R</sub>	40	500		$V_R = 600 \text{ V}, T_j = 175 \text{ °C}$	
Total Capacitive Charge	Q <sub>c</sub>	3.3		nC	V <sub>R</sub> = 600 V, T <sub>j</sub> = 25 °C	Fig. 5
		80			$V_R = 0 \text{ V}, T_j = 25 \text{ °C}, f = 1 \text{ MHz}$	
Total Capacitance	С	11		pF	$V_R = 200 \text{ V}, T_j = 25 \text{ °C}, f = 1 \text{ MHz}$	Fig. 6
		8.5			$V_R = 400 \text{ V}, T_j = 25 \text{ °C}, f = 1 \text{ MHz}$	

#### Notes:

SiC Schottky Diodes are majority carrier devices, so there is no reverse recovery charge.

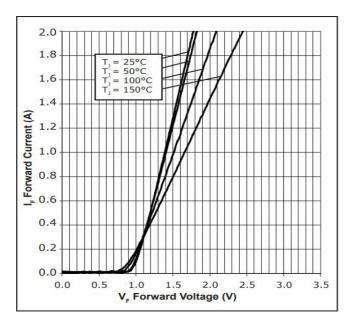
### **Thermal & Mechanical Characteristics**

Parameter	Symbol	Value	Unit	Notes
Thermal Resistance, Junction to Case (Typical)	R <sub>e, JC (TYP)</sub>	7	°C/W	
Junction Temperature	T <sub>j</sub>	-55 to +175	°C	
Case & Storage Temperature	T <sub>c</sub>	-55 to +175		
		1	Nm	M3 Screw
TO-220 Mounting Torque	-	8.8	lbf-in	6-32 Screw

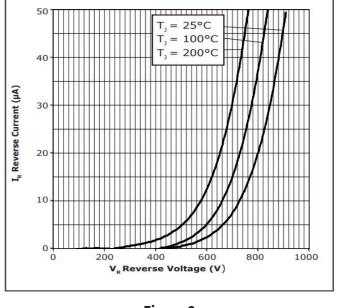
## **Electrostatic Discharge (ESD) Classifications**

Parameter	Symbol	Notes
Human Body Model	НВМ	Class 3B (≥ 8000 V)
Charge Device Model	CDM	Class C3 (≥ 1000 V)

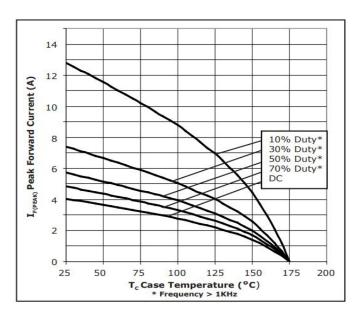
## **Typical Performance**



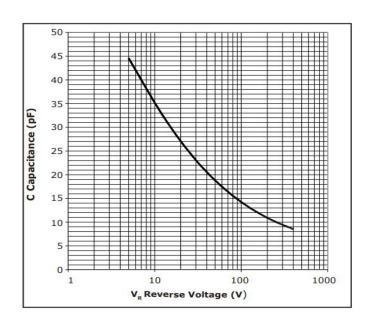
**Figure 1**Forward Characteristics



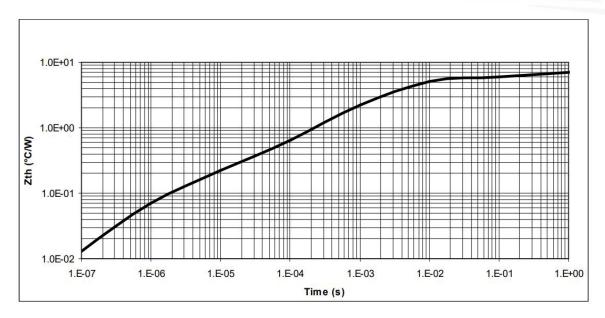
**Figure 2**Reverse Characteristics



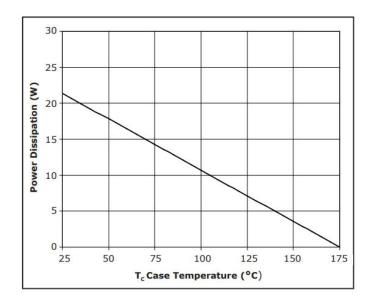
**Figure 3**Current Derating



**Figure 4**Capacitance vs. Reverse Voltage



**Figure 5**Transient Thermal Impedance



**Figure 6**Power Derating

### **Diode Model**

$$\begin{array}{c|c} - & & \\ \hline V_T & & R_T \\ \end{array}$$

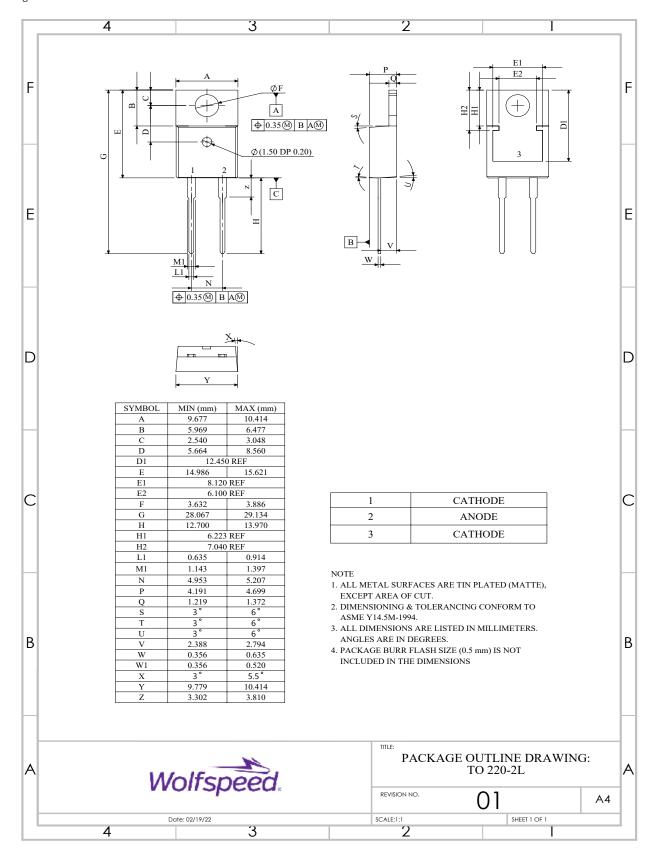
$$Vf_T = V_T + If R_T$$

$$\begin{split} V_{T=}\, 0.94 + & \left(T_{\rm j} \, * \, \text{-} 1.2 \, {}^{\text{+}} 10^{\text{-}3}\right) \\ R_{T=}\, 0.015 + & \left(T_{\rm j} \, * \, 6.4 \, {}^{\text{+}} 10^{\text{-}3}\right) \end{split}$$

Note:  $T_j$  = Diode Junction Temperature In Degrees Celsius

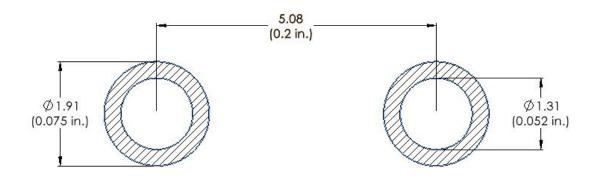
## **Package Dimensions & Pin-Out**

Package: TO-220-2



## **Recommended Solder Pad Layout**

Primary dimensions shown in mm.



# **Product Ordering Information**

Order Number	Packing Type
CSD01060A	Tube

# **Revision History**

Document Version	Date of Release	Description of Changes
1	October-2019	Initial Release
18	March-2023	Update Package Drawing Update Landing Pad

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